# 5-104178-1 - ACTIVE

#### AMPMODU | AMPMODU System 50

TE Internal #: 5-104178-1 PCB Mount Header, Vertical, Board-to-Board, 4 Position, 1.27 mm [. 05 in] Centerline, Unshrouded, Gold, Through Hole - Solder, AMPMODU System 50

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Connectors > PCB Connectors > PCB Headers & Receptacles



#### PCB Connector Assembly Type: PCB Mount Header

PCB Mount Orientation: Vertical

Connector System: Board-to-Board

Number of Positions: **4** 

Number of Rows: 1

### Features

#### Product Type Features

PCB Connector Assembly Type

Connector System

Header Type

PCB Mount Header

Board-to-Board

Unshrouded

Sealable	No	
Connector & Contact Terminates To	Printed Circuit Board	
Configuration Features		
Connector Contact Load Condition	Fully Loaded	
PCB Mount Orientation	Vertical	
Number of Positions	4	
Number of Rows	1	
Board-to-Board Configuration	Parallel	
Electrical Characteristics		
Dielectric Withstanding Voltage (Max)	500 VAC	
Insulation Resistance	5000 MΩ	
Operating Voltage	30 VAC	
Body Features		
Primary Product Color	Black	
Contact Features		

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Mating Square Post Dimension	.38 mm[.015 in]	
PCB Contact Termination Area Plating Material Thickness	3.81 – 6.35 μm[150 – 250 μin]	
PCB Contact Termination Area Plating Material Finish	Matte	
Contact Shape & Form	Rectangular	
Contact Underplating Material	Nickel	
PCB Contact Termination Area Plating Material	Tin	
Contact Base Material	Copper Alloy	
Contact Mating Area Plating Material	Gold	
Contact Mating Area Plating Material Thickness	.76 μm[30 μin]	
Contact Type	Pin	
Contact Current Rating (Max)	3.6 A	
Termination Features		
Round Termination Post & Tail Diameter	.38 mm[.015 in]	
Termination Post & Tail Length	2.54 mm[.1 in]	
Termination Method to Printed Circuit Board	Through Hole - Solder	
Mechanical Attachment		
Mating Alignment	Without	
PCB Mount Retention	Without	
PCB Mount Alignment	Without	
Connector Mounting Type	Board Mount	
Housing Features		
Centerline (Pitch)	1.27 mm[.05 in]	
Housing Material	LCP	
Dimensions		
PCB Thickness (Recommended)	1.57 mm[.062 in]	
Usage Conditions		
Housing Temperature Rating	High	
Operating Temperature Range	-65 – 105 °C[-85 – 221 °F]	
Operation/Application		
Solder Process Feature	Board Standoff	
Circuit Application	Signal	
Industry Standards		

**C** For support call+1 800 522 6752

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UL Rating	Recognized
Agency/Standard	CSA, UL
Approved Standards	CSA LR7189, UL E28476
UL Flammability Rating	UL 94V-0
Packaging Features	
Packaging Quantity	400
Packaging Type	Box, Carton
EU RoHS Directive 2011/65/EU	
EU RoHS Directive 2011/65/EU	
	Compliant
EU ELV Directive 2000/53/EC	Compliant Compliant
EU ELV Directive 2000/53/EC China RoHS 2 Directive MIIT Order No 32, 2016	·
	Compliant

Free Free

#### Solder Process Capability

Wave solder capable to 260°C

#### Product Compliance Disclaimer

This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' posted at this URL: https://echa.europa.eu/guidance-documents/guidance-on-reach

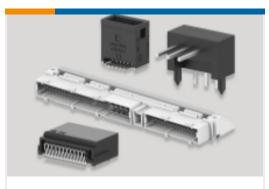
## **Compatible Parts**

PCB Mount Header, Vertical, Board-to-Board, 4 Position, 1.27 mm [.05 in] Centerline, Unshrouded, Gold, Through Hole - Solder, AMPMODU System 50





Also in the Series AMPMODU System 50



PCB Headers & Receptacles(1012)

## Customers Also Bought



TE Part #6609069-3	TE Part #1-6609021-4	TE Part #1658608-3	TE Part #1-1734592-0
16FC10 J0=F7740	30VB6=F7355 S0	15 POS HDF PLUG, MS, LEAD FREE	FPC CONN. 0.5MM PITCH B/C, 10P
2222		13 222 14 15 222 15 15 15 15 15 15 15 15 15 15 15 15 15	TE TE
TE Part #1623693-1	TE Part #104483-1	TE Part #1676480-3	TE Part #6-1393250-8
CRG1206 ZEROHM	08 SHORT PT RCPT HSG DR .100CL	CRG0402 1% 10K	W28-XT1A-3=W28



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## Documents

Product Drawings 04 SYS 50 HDR SRST UNSHRD SN

English

Datasheets & Catalog Pages

AMPMODU\_INTERCONNECTION\_SYSTEM\_SECTION3AND4

English

AMPMODU SYSTEM 50 QUICK REFERENCE GUIDE

English

AMPMODU SYSTEM 50

English

**Product Specifications** 

**Application Specification** 

English

Product Environmental Compliance TE Material Declaration

English